

30V N-Channel Trench MOSFET

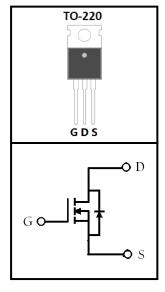
FEATURES

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Hard switched and high frequency circuits





Device Marking and Package Information						
Device	Package	Marking				
CTP03N2P7	TO-220	CTP03N2P7				

Absolute Maximum Ratings at T_j = 25°C unless otherwise noted							
Parameter		Symbol Value		Unit			
Drain-Source Voltage (V _{GS} = 0V)		V_{DSS}	30	V			
Continuous Drain Current T _C = 25°C	(note1)		230	А			
Continuous Drain Current T _C = 100°C	(note1)	I _D	150	А			
Pulsed Drain Current	(note2)	I _{DM}	500	А			
Gate Source Voltage		V_{GSS}	±20	V			
Single Pulse Avalanche Energy (note3)		E _{AS}	246	mJ			
Power Dissipation $T_C = 25^{\circ}C$ (note4)		P_{D}	187	W			
Operating Junction and Storage Temperatu	re Range	T_J,T_stg	-55~+175	°C			

Thermal Characteristics						
Parameter	Symbol	Value	Unit			
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	0.8	°C/W			
Thermal Resistance, Junction-to-Ambient	(note1)	$R_{\theta JA}$	62	30/00		



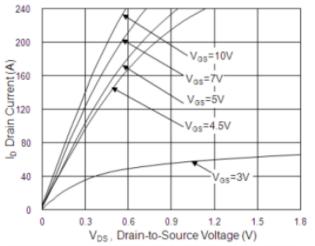
Parameter	Symbol	Test Conditions	Value			Unit	
			Min.	Тур.	Max.		
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250\mu A$	30			V	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	uA	
2010 Gato Voltago Brain Garront	פטי	$V_{DS} = 30V, V_{GS} = 0V, T_{J} = 55^{\circ}C$			5	uA	
Gate-Source Leakage	$I_{\rm GSS}$	$V_{GS} = \pm 20V$			±100	nA	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0		2.5	V	
Drain Course On Decistones (note2)	D	$V_{GS} = 10V, I_{D} = 30A$		2.0	2.7	mΩ	
Drain-Source On-Resistance (note2)	$R_{DS(on)}$	$V_{GS} = 4.5V, I_{D} = 15A$		2.6	3.8	mΩ	
Dynamic							
Input Capacitance	C _{iss}	V _{GS} = 0V,		5850		pF	
Output Capacitance	C _{oss}	$V_{DS} = 15V$,		720			
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		525			
Total Gate Charge (4.5V)	Q_g			56.9		пС	
Gate-Source Charge	Q_{gs}	$V_{DS} = 15V, I_{D} = 15A,$ $V_{GS} = 4.5V$		13.8			
Gate-Drain Charge	Q_{gd}			23.5			
Turn-on Delay Time	t _{d(on)}			20.1		ns	
Turn-on Rise Time	t _r	V _{DS} = 15V. I _D = 1A		6.3			
Turn-off Delay Time	t _{d(off)}	$V_{DS} = 15V, I_{D} = 1A$ $V_{GS} = 10V, R_{G} = 3\Omega$		124.6			
Turn-off Fall Time	t _f			15.8			
Body Diode Characteristics							
Source-Drain Current(Body Diode)	I _{SD}				230	А	
Pulsed Source-Drain Current(Body Diode)	I _{SDM}				500		
Body Diode Voltage	V_{SD}	$T_J = 25^{\circ}C$, $I_{SD} = 1A$, $V_{GS} = 0V$			1.2	V	

Notes

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width $\!\leq\!300 us$, duty cycle $\!\leq\!2\%$
- 3. The EAS data shows Max. rating . The test condition is VDD =25V,VGS =10V,L=0.1mH $\,$
- 4. The power dissipation is limited by 175°C junction temperature
- 5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.



Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted



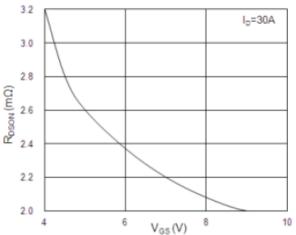


Fig.1 Typical Output Characteristics



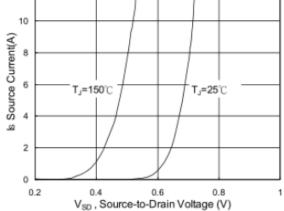


Fig.2 On-Resistance vs. G-S Voltage

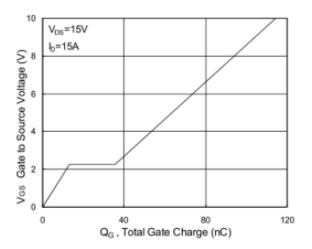


Fig.3 Forward Characteristics of Reverse Diode

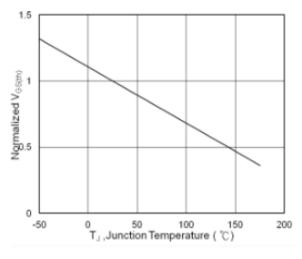


Fig.5 Normalized V_{GS(th)} vs. T_J

Fig.4 Gate-Charge Characteristics

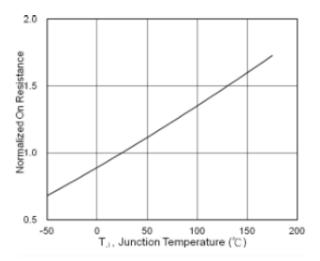
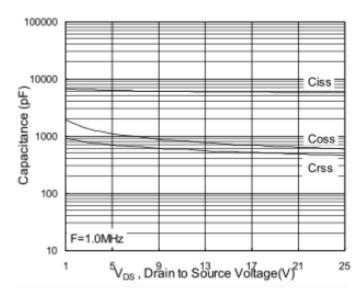


Fig.6 Normalized RDSON vs. TJ



Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted



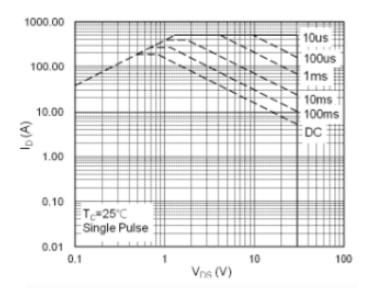


Fig.7 Capacitance

Fig.8 Safe Operating Area

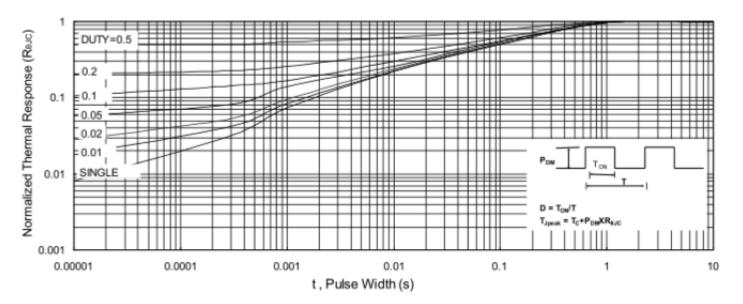


Fig.9 Normalized Maximum Transient Thermal Impedance



Figure A: Gate Charge Test Circuit and Waveform

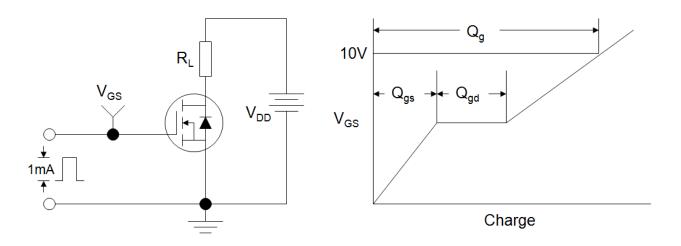


Figure B: Resistive Switching Test Circuit and Waveform

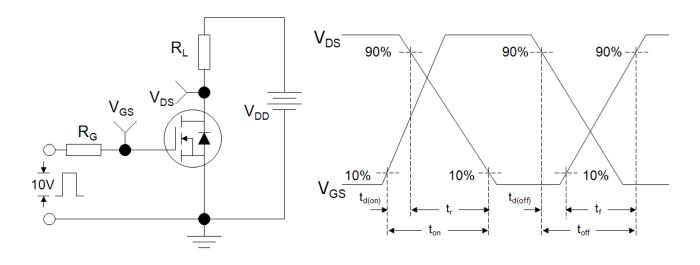
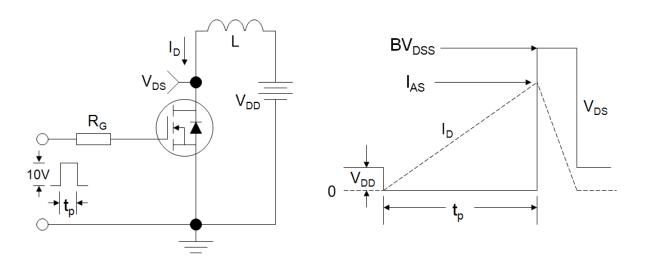
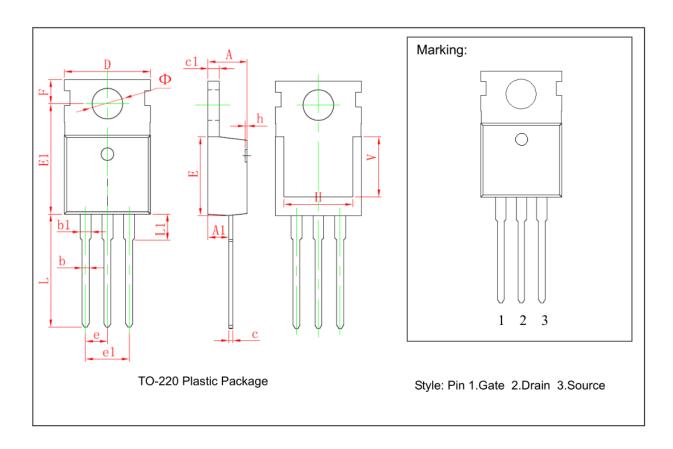


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





TO-220 Dimension



DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.	וווט	Min.	Max.	Min.	Max.
Α	4.400	4.600	0.173	0.181	е	2.540*		0.100*	
A1	2.250	2.550	0.089	0.100	e1	4.980	5.180	0.196	0.204
b	0.710	0.910	0.028	0.036	F	2.650	2.950	0.104	0.116
b1	1.170	1.370	0.046	0.054	Н	7.900	8.100	0.311	0.319
С	0.330	0.650	0.013	0.026	h	0.000	0.300	0.000	0.012
c1	1.200	1.400	0.047	0.055	L	12.900	13.400	0.508	0.528
D	9.910	10.250	0.390	0.404	L1	2.850	3.250	0.112	0.128
E	8.950	9.750	0.352	0.384	V	7.500 REF		0.295 REF	
E1	12.650	12.950	0.498	0.510	Φ	3.600	3.800	0.142	0.150



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